

10/520218

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U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

**INFORMATION DISCLOSURE
STATEMENT**

Docket Number
10191/3828

Application Number
To Be Assigned

Filing Date
Herewith

Examiner
To Be Assigned

Art Unit
To Be Assigned

Invention Title
ELECTRICAL COMPONENT, IN PARTICULAR
HIGH-FREQUENCY MICROELECTRONIC OR
MICROELECTROMECHANICAL COMPONENT,
AND METHOD FOR MANUFACTURING THE SAME

Inventor(s)
BREITSCHWERDT et al.

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

1. In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and in conformance with the procedures of 37 C.F.R. §§ 1.97 and 1.98 and M.P.E.P. § 609, attorneys for Applicants hereby bring the following references to the attention of the Examiner. The references are listed on the attached modified PTO form 1449. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.
2. A copy of each foreign patent, publication or other information listed on the modified PTO form 1449 is enclosed.

Dated: 1/3/05

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The PTO did not receive the following
listed item(s) indicated FORS & NPLs

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INFORMATION DISCLOSURE STATEMENT BY APPLICANTS PTO FORM 1449	Atty. Docket No. 10191/3828	Serial No. 10/520218 To Be Assigned
	Applicant(s) BREITSCHWERDT et al.	
	Filing Date Herewith	Group To Be Assigned

U. S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE
	4,348,253**	Sep. 7, 1982	Subbarao et al.			
	5,618,752**	Apr. 8, 1997	Gaul			
	5,913,134**	Jun. 15, 1999	Drayton et al.			
	6,207,903**	Mar. 27, 2001	Wen et al.			
	6,225,651**	May 1, 2001	Billon			
	6,365,513**	Apr. 2, 2002	Furukawa et al.			

**Described in the Specification; copy not provided pursuant to Official Gazette notice dated August 5, 2003.

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION	
						YES	NO
*	99/62135*	Dec. 2, 1999	PCT				
*	2002/185201*	Jun. 28, 2002	Japan				
	02/33782**	Apr. 25, 2002	PCT				
	42 41 045**	May 26, 1994	Germany			X (Abstract)	
	100 37 385**	Feb. 14, 2002	Germany			X (Abstract)	

* Copy of reference is not enclosed because reference is cited in Search Report (copy of reference provided by International Searching Authority).

**Described in the Specification.

OTHER DOCUMENTS

EXAMINER'S INITIALS	AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
*	Abhari et al, <i>Analysis of Microvia Interconnects</i> , Microwave Smposium Digest, 1998 IEEE MTT-S International, Baltimore, MD, pgs. 1925-8.*
*	Goverdhanam et al., <i>Novel Three-Dimensional Vertical Interconnect Technology for Microwave and RF Applications</i> , Microwave Smposium Digest, 1999 IEEE MTT-S International, Anaheim, CA, Vol. 2, pgs 641-4.*
*	Turner et al., <i>Selective Plasma Etching of SI from Gaas-on-SI Wafers for Microwavevia-Hole Formation</i> , Electronics Letters, IEE Stevenage, GB, Vol. 26, No. 13, pgs 854-5.*
	J.P. Quine, <i>Characterization of Via Connections in Silicon Circuit Boards</i> , IEEE Transactions in Microwave Theory and Techniques, January 1988, Vol. 36, No. 1, pgs. 21-7.**

* Copy of reference is not enclosed because reference is cited in Search Report (copy of reference provided by International Searching Authority).

** Described in the Specification

EXAMINER	DATE CONSIDERED
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	